





**DETERGENT COMPOSITION**

**Patent number:** WO0197268  
**Publication date:** 2001-12-20  
**Inventor:** SAKAI AKIMITSU [JP]; TAMURA ATSUSHI [JP]  
**Applicant:** KAO CORP [JP]; SAKAI AKIMITSU [JP]; TAMURA  
ATSUSHI [JP]  
**Classification:**  
- **international:** H01L21/304; C11D7/34; C11D7/26  
- **european:** C11D3/00B8; C11D7/02; C11D7/26; C11D7/26E;  
C11D7/26K; C11D7/34; C11D11/00B2D8  
**Application number:** WO2001JP05091 20010614  
**Priority number(s):** JP20000181141 20000616

**Also published as:**

 EP1310989 (A1)  
 US2003158059 (A1)

**Cited documents:**

 JP11138113  
 JP11330023

**Abstract of WO0197268**

A detergent composition which is less apt to corrode wiring materials and is highly effective in cleansing a semiconductor substrate or semiconductor element having fine particles or impurity metal particles adherent thereto. The detergent composition contains a reducing agent and has an oxidation-reduction potential (25 DEG C) of +0.2 V or lower and a pH (25 DEG C) of 3 to 12. Also provided is a method of cleansing a semiconductor substrate or semiconductor element with the detergent composition.

Data supplied from the esp@cenet database - Worldwide